



100% Material Declaration Data Sheet for 7 Series FFG1927

PK558 (v1.1) November 23, 2012

Average Weight: 24.9750g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.828955	3.319
	Silicon (Si)	7440-21-3	100.00	Basis	0.828955	
Solder Bump					0.038857	0.156
	Tin (Sn)	7440-31-5	63.00	Basis	0.024480	
	Lead (Pb)	7439-92-1	37.00	Basis	0.014377	
Solder Paste					0.014100	0.056
	Tin (Sn)	7440-31-5	96.50	Basis	0.013607	
	Silver (Ag)	7440-22-4	3.00	Basis	0.000423	
	Copper (Cu)	7440-50-8	0.50	Basis	0.000071	
Capacitor 1					0.041280	0.165
	BaTiO3 type	12047-27-7	70.60	Ceramic	0.029144	
	Nickel (Ni)	7440-02-0	6.70	Inner electrode	0.002766	
	Copper (Cu)	7440-50-8	20.10	Outer electrode	0.008297	
	Nickel (Ni)	7440-02-0	0.80	Plating 1	0.000330	
	Tin (Sn)	7440-31-5	1.80	Plating 2	0.000743	
Capacitor 2					0.015200	0.061
	BaTiO3 type	12047-27-7	61.70	Ceramic	0.009378	
	Nickel (Ni)	7440-02-0	4.89	Inner electrode	0.000743	
	Indium tin oxide	50926-11-9	18.30	Outer electrode	0.002782	
	Copper (Cu)	7440-50-8	13.40	Outer electrode	0.002037	
	Nickel (Ni)	7440-02-0	0.49	Plating 1	0.000074	
	Tin (Sn)	7440-31-5	1.22	Plating 2	0.000185	
Capacitor 3					0.012000	0.048
	BaTiO3 type	12047-27-7	66.00	Ceramic	0.007920	
	Nickel (Ni)	7440-02-0	2.67	Inner electrode	0.000320	
	Copper (Cu)	7440-50-8	23.33	Outer electrode	0.002800	
	Nickel (Ni)	7440-02-0	2.33	Plating 1	0.000280	
	Tin (Sn)	7440-31-5	5.67	Plating 2	0.000680	

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Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Capacitor 4					0.011160	0.045
	BaTiO3 type	12047-27-7	51.10	Ceramic	0.005703	
	Nickel (Ni)	7440-02-0	27.00	Inner Electrode	0.003013	
	Copper (Cu)	7440-50-8	16.00	Outer Electrode	0.001786	
	Glass	65997-17-3	0.90		0.000100	
	Nickel (Ni)	7440-02-0	2.00	Plating1	0.000223	
	Tin (Sn)	7440-31-5	3.00	Plating2	0.000335	
Underfill					0.082000	0.328
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.00	Basis	0.016400	
	Phenolic Resin	Trade Secret	15.00	Basis	0.012300	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00	Basis	0.004100	
	Amine type accelerator	Trade Secret	5.00	Basis	0.004100	
	Silicon Dioxide	60676-86-0	51.50	Basis	0.042230	
	Carbon Black	1333-86-4	1.00	Basis	0.000820	
	Additives	Trade Secret	2.50	Additive	0.002050	
Lid					14.214000	56.913
	Copper (Cu)	7440-50-8	99.15	Main Material	14.093181	
	Nickel (Ni)	7440-02-0	0.85	Main Material	0.120819	
Lid Adhesive					0.340000	1.361
	Aluminium Oxide Al2O3	1344-28-1	70.00	Main Material	0.238000	
	Dimethyl siloxane, dimethylvinyl-terminated	68083-19-2	30.00	Main Material	0.102000	
Solder Ball					1.607244	6.435
	Tin (Sn)	7440-31-5	96.50	Main Material	1.550990	
	Silver (Ag)	7440-22-4	3.00	Main Material	0.048217	
	Copper (Cu)	7440-50-8	0.50	Main Material	0.008036	
Substrate					7.770204	31.112
	Copper (Cu)	7440-50-8	44.97		3.494261	
	Tin (Sn)	7440-31-5	0.08		0.006216	
	Lead (Pb)	7439-92-1	0.11		0.008547	
	Silver (Ag)	7440-22-4	0.52		0.040405	
	BT Core	N/A	43.68		3.394025	
	ABF	N/A	9.53		0.740501	
	Solder Mask	N/A	1.11		0.086249	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
06/05/2012	1.0	Initial Xilinx release
11/23/2012	1.1	Update substrate component

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